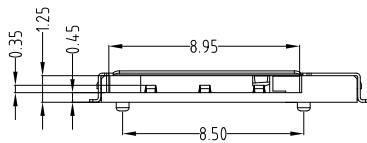
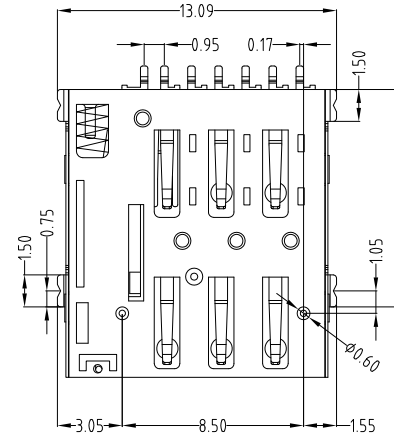
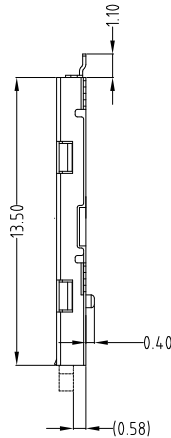
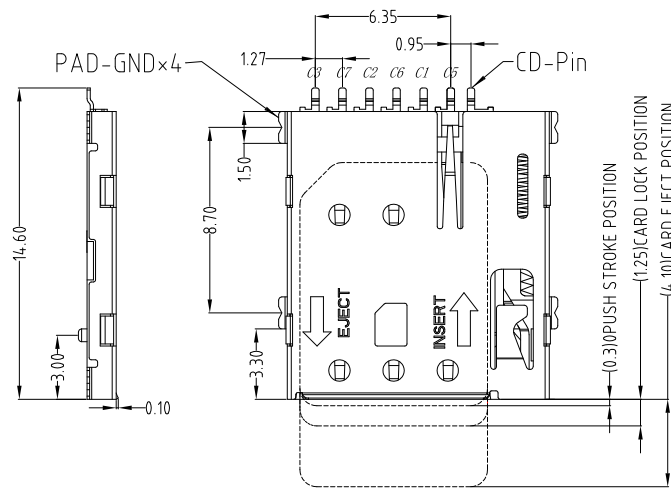
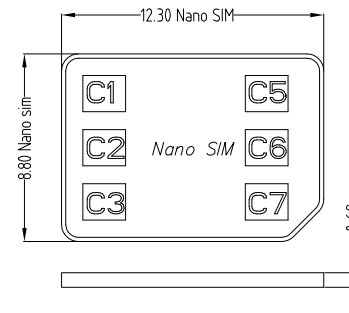


P.C.B LAYOUT



SIM pin assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



SPECIFICATION:

1. CURRENT RATING : 0.5A MAX.
2. VOLTAGE RATING : 125V AC / DC
3. INSULATION RESISTANCE : 1000MΩ MIN.
4. CONTACT RESISTANCE : 100mΩ MAX.
5. OPERATING TEMPERATURE RANGE : -40°C TO +80°C.
6. STORAGE TEMPERATURE RANGE : -20°C TO +70°C.

MATERIALS:

1. HOUSING : LCP
2. CONTACT : PHOSPHOR BRONZE
3. SHELL : SUS

Finish:

1. Finish: CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
2. SHELL: NICKEL UNDER PLATED SURFACE LAYER



TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD. ANGEL'S



UNITS MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao
DATE: 12/27/23
DATE: 12/27/23
DATE: 12/27/23

MAT'L	TITLE	CONNECTOR
	MODLE	Nano SIM CARD PUSH PUSH H1.37
SCALE	DWG NO.	NSIM-019107A-S267
SHEET NO.	PART NO.	NSIM-019107A-S267

ITEM NO.	DESCRIPTION	DRAWN	DATE